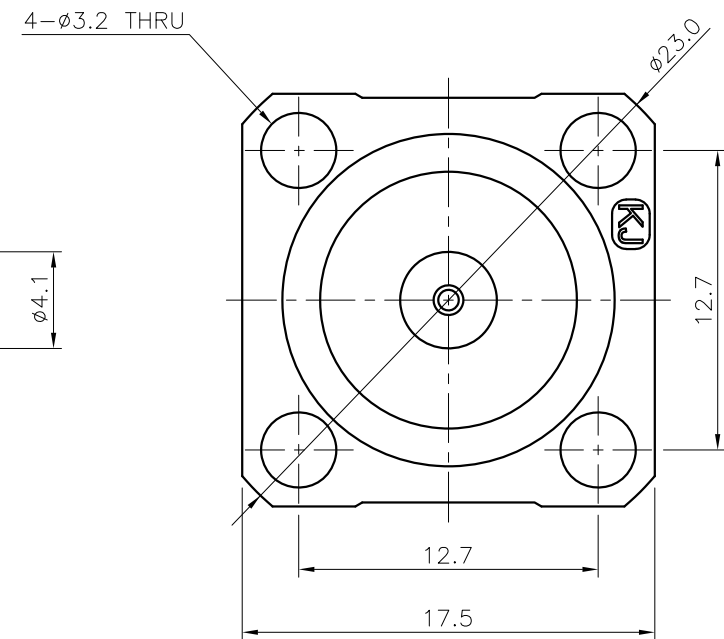
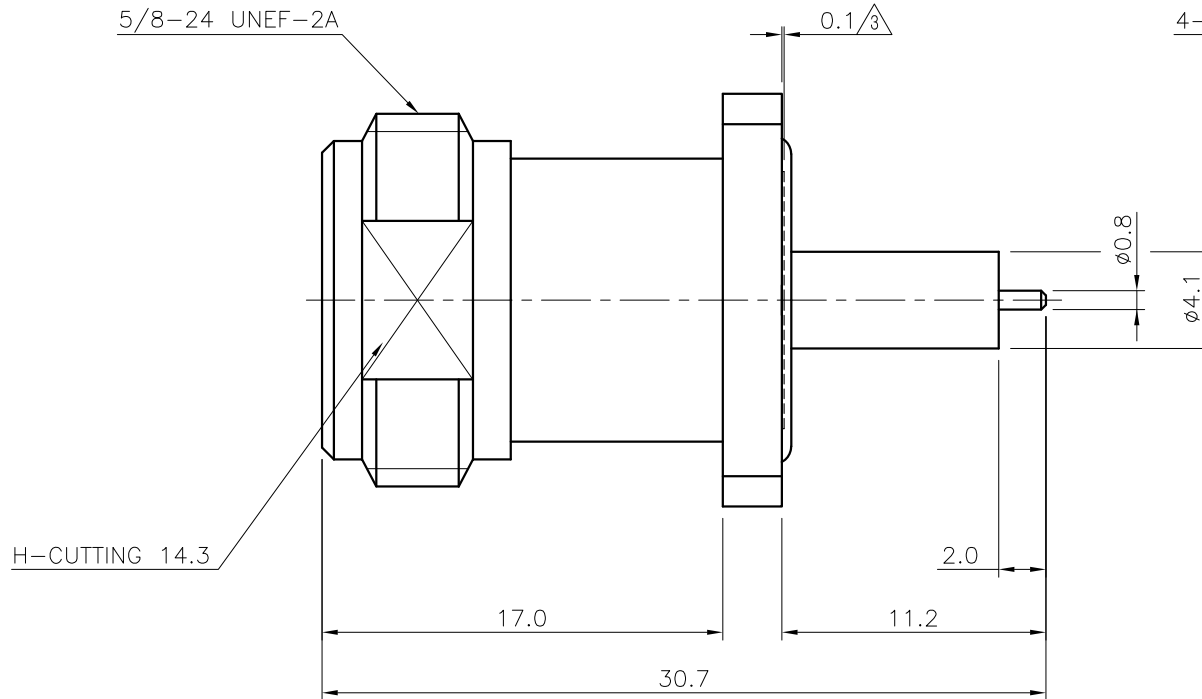


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2019.10.21.
1	[설변No.202001-0007] 절연체 조립 시 돌출개선으로 인한 치수변경	S.Y.EUN	I.C.KIM	2020.01.22.
2	[설변No.202012-0002] O-RING 빠짐 개선 안착부 금형수정	I.C.KIM		2020.12.07.
3	[설변No.202101-0003] O-RING 빠짐 개선 안착부 0.1mm Ground Boss 추가	S.Y.EUN	I.C.KIM	2021.01.20.
4	[설변지리No.202403-0001] 조립 후 절연체 및 핀 치수 Out 개선 - 절연체 및 핀 치수 변경	S.H.KIM		2024.03.08.



5	GASKET	1	SILICONE RUB	RED	DGK00257-N/2
4	RING	1	MBsBD C3604BD-F	Nickel Plate	DSR01097-5/4 DSR01097-5/3
3	INSULATOR	1	TEFLON		DIN02840-N/8
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03768-5/6 DCT03768-5/5
1	BODY	1	ZnDC	Nickel Plate (3~4μm)	DBD02992-5/3 DBD02992-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 03. 08.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle ±1°	APPROVED BY					
MATERIAL _____		CHECKED BY			TITLE N50 SOLDER END JS-4H		
		DRAWN BY S.H.KIM					
FINISH _____		SCALE 3/1	UNIT mm		A4	DWG NO. CN03958-7/A	
						REVISION 4	SHEET 1 of 1